









CEP2515

150V ▲ 60mΩ ▲ 27A ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type
N-channel enhancement mode
UL94V-0 rated flame retardant epoxy
TO220-3L package

Super high dense cell density for extremely low R_{DS(ON)} **High power and current handling capability**

MAXIMUM RATINGS

Parameter (T_c = 25°C, unless otherwise noted)		Characteristics
Drain-Source Voltage	V _{DS}	150V
Gate-Source Voltage	V_{GS}	±30V
Continuous Drain Current at T _C = 25°C	l _D	27A
Pulsed Drain Current Note 1	I _{DM} Note 4	108A
Maximum Power Dissipation at T _C = 25°C	P _D	104W
Power Dissipation Derating above 25°C	ΔP_D	0.83W/°C
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +150°C

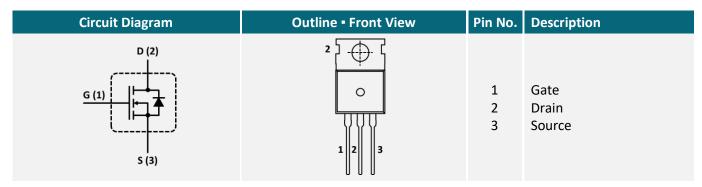
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R _{TH_JC}	1.2°C/W
Thermal Resistance, Junction-to-Ambient Note 2	R _{TH_JA}	62.5°C/W

APPLICATIONS

Battery Management Systems	E-Bike	Industrial Control	Power Inverter	UPS
+4-	50			

PIN DESCRIPTION





ELECTRICAL CHARACTERISTICS ▲ T_C = 25°C, unless otherwise noted

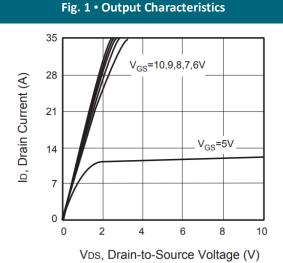
ltem	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$	BV_{DSS}	150			V
Zero Gate Voltage Drain Current	$V_{DS} = 135V, V_{GS} = 0V$	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 30V$, $V_{DS} = 0V$	I _{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	I _{GSSR}			-100	nA
On Characteristics Note 2						
Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_{D} = 250 \mu A$	$V_{GS(th)}$	2		4	V
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 10A$	R _{DS(ON)}		60	80	mΩ
Static Drain-Source On-Resistance	$V_{GS} = 7V$, $I_{D} = 10A$	R _{DS(ON)}		62	90	mΩ
Dynamic Characteristics Note 3						
Input Capacitance	$V_{DS} = 75V$, $V_{GS} = 0V$, $f = 1MHz$	C _{ISS}		1225		pF
Output Capacitance	$V_{DS} = 75V$, $V_{GS} = 0V$, $f = 1MHz$	Coss		105		pF
Reverse Transfer Capacitance	$V_{DS} = 75V$, $V_{GS} = 0V$, $f = 1MHz$	C_{RSS}		50		pF
Switching Characteristics Note 3						
Turn-On Delay Time	$V_{DD} = 75V$, $V_{GS} = 10V$, $I_D = 10A$, $R_{G(ext)} = 6\Omega$	t _{D(ON)}		17		ns
Turn-On Rise Time	V_{DD} = 75V, V_{GS} = 10V, I_D = 10A, $R_{G(ext)}$ = 6Ω	t _R		6		ns
Turn-Off Delay Time	$V_{DD} = 75V$, $V_{GS} = 10V$, $I_D = 10A$, $R_{G(ext)} = 6\Omega$	t _{D(OFF)}		33		ns
Turn-Off Fall Time	$V_{DD} = 75V$, $V_{GS} = 10V$, $I_{D} = 10A$, $R_{G(ext)} = 6\Omega$	t _F		6		ns
Total Gate Charge	$V_{DS} = 75V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{G}		26		nC
Gate Source Charge	$V_{DS} = 75V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{GS}		5		nC
Gate Drain Charge	$V_{DS} = 75V$, $V_{GS} = 10V$, $I_D = 10A$	Q_{GD}		9		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current		Is			27	А
Drain-Source Diode Forward Voltage Note 2	V _{GS} = 0V, I _S = 22A	V_{SD}			1.5	V

Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3: Guaranteed by design, not subject to production testing.
- 4: Pulse width limited by safe operating area.



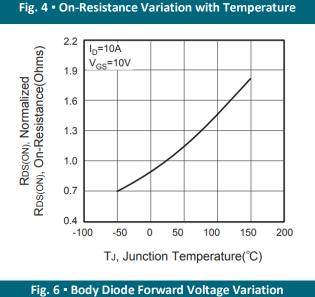
REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

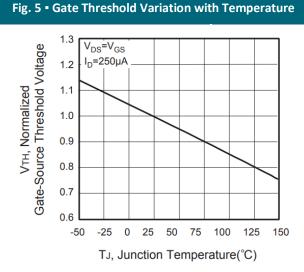


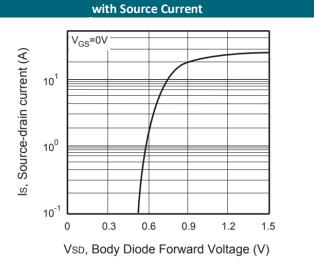
25°C T_J=125°C Vos, Gate-to-Source Voltage (V)

Fig. 2 • Transfer Characteristics

Fig. 3 • Capacitance C, Capacitance (pF) Ciss Coss VDS, Drain-to-Source Voltage (V)







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REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

Fig. 7 • Gate Charge

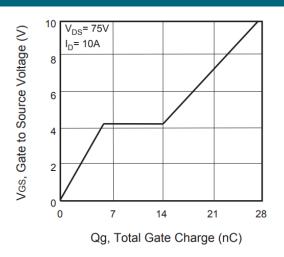


Fig. 8 • Maximum Safe Operating Area

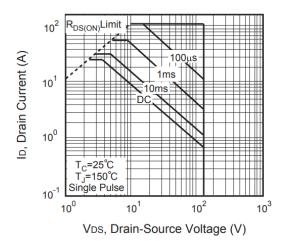
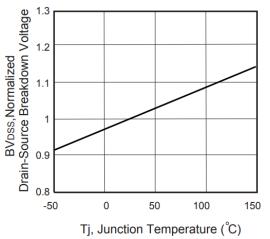


Fig. 9 • Breakdown Voltage Variation vs. Temperature





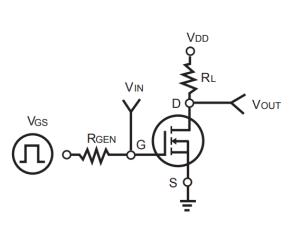
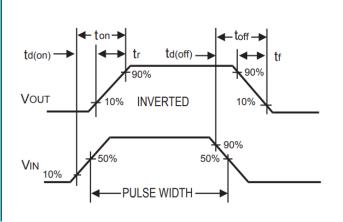


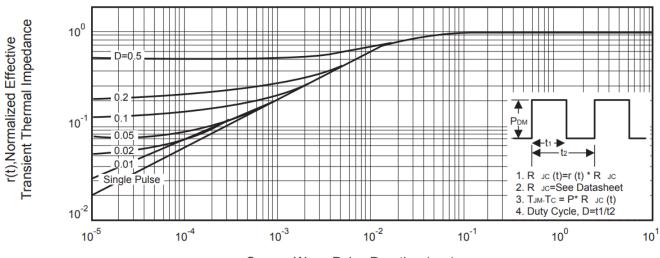
Fig. 11 • Switching Waveforms





REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

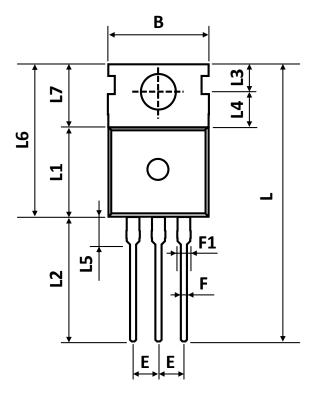
Fig. 12 • Normalized Thermal Transient Impedance Curve

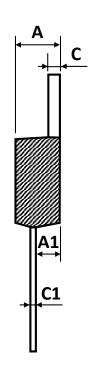


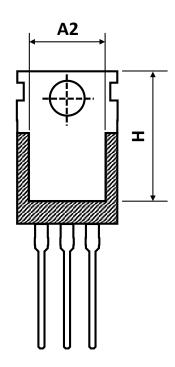
Square Wave Pulse Duration (sec)



PACKAGE OUTLINE







Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	4.43	4.53	4.63
A1	2.30	2.40	2.50
A2	7.70	7.90	8.10
В	9.80	10.00	10.20
С	1.25	1.30	1.40
C1	0.45	0.50	0.60
D	3.45	3.60	3.70
E	2.45	2.54	2.60
F	0.70	0.80	0.95
F1	1.15	1.33	1.50
L	26.80	28.80	30.80
L1	9.20	9.30	9.40
L2	12.80	13.10	13.40
L3	2.70	2.80	2.90
L4	3.50	3.70	3.80
L5	2.60	2.90	3.20
L6	15.40	15.80	16.20
L7	6.20	6.50	6.80
Н	12.95	13.25	13.55

ORDERING INFORMATION

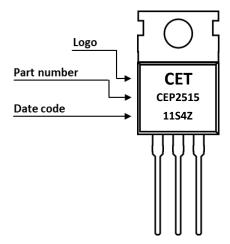
Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
CEP2515	TO-220-3L	Tube	50pcs	1,000pcs	4,000pcs

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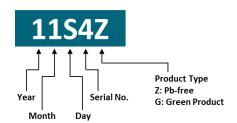


PART MARKING



DATE CODE

Example: 11S4Z



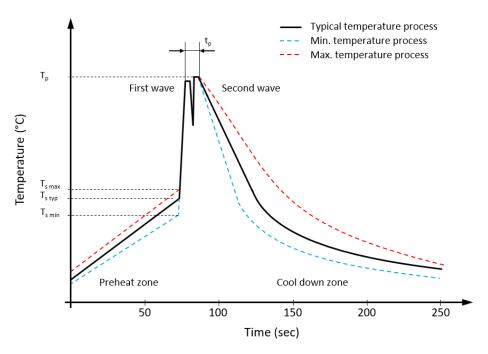


Coding list for "Day"





RECOMMENDED WAVE SOLDERING PROFILE A THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	$T_{s min}$	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	T _{s max}	130 °C	130 °C
Preheat time t_s from T_{smin} to T_{smax}	ts	70 seconds	70 seconds
Peak temperature	Tp	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t _p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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